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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/010,237	12/07/2001	Bidyut K. Sen	03226/092001	5837	
32615	7590 03/08/2004		EXAM	EXAMINER	
OSHA NOVAK & MAY L.L.P./SUN			LEWIS, N	LEWIS, MONICA	
1221 MCKINNEY, SUITE 2800 HOUSTON, TX 77010			ART UNIT	PAPER NUMBER	
•			2822		
			DATE MAILED: 03/08/2004		

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)				
	10/010,237	SEN, BIDYUT K.				
Office Action Summary	Examiner	Art Unit				
	Monica Lewis	2822				
The MAILING DATE of this communication appeared for Reply	ppears on the cover sheet with the c	orrespondence address				
A SHORTENED STATUTORY PERIOD FOR REP THE MAILING DATE OF THIS COMMUNICATION  - Extensions of time may be available under the provisions of 37 CFR of after SIX (6) MONTHS from the mailing date of this communication.  - If the period for reply specified above is less than thirty (30) days, a relative to reply within the set or extended period for reply will, by statuent Any reply received by the Office later than three months after the mail earned patent term adjustment. See 37 CFR 1.704(b).	I.  .136(a). In no event, however, may a reply be tin  sply within the statutory minimum of thirty (30) day d will apply and will expire SIX (6) MONTHS from tte, cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. D (35 U.S.C. § 133).				
Status						
1) Responsive to communication(s) filed on 17	October 2003.					
•—						
closed in accordance with the practice under	closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims						
4) ☐ Claim(s) 1-17 is/are pending in the application 4a) Of the above claim(s) is/are withdreds 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-17 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and	awn from consideration.					
Application Papers						
9)☐ The specification is objected to by the Examination 10)☑ The drawing(s) filed on <u>07 December 2001</u> is Applicant may not request that any objection to the Replacement drawing sheet(s) including the correction. The oath or declaration is objected to by the	/are: a)⊠ accepted or b)□ object the drawing(s) be held in abeyance. Sec ection is required if the drawing(s) is ob	e 37 CFR 1.85(a). jected to. See 37 CFR 1.121(d).				
Priority under 35 U.S.C. § 119						
12) ☐ Acknowledgment is made of a claim for foreignal All b) ☐ Some * c) ☐ None of:     1. ☐ Certified copies of the priority docume 2. ☐ Certified copies of the priority docume 3. ☐ Copies of the certified copies of the prapplication from the International Bure * See the attached detailed Office action for a list	nts have been received. nts have been received in Applicati iority documents have been receive au (PCT Rule 17.2(a)).	ion No ed in this National Stage				
Attachment(s)						
1) Notice of References Cited (PTO-892)	4) ☐ Interview Summary Paper No(s)/Mail D					
<ol> <li>Notice of Draftsperson's Patent Drawing Review (PTO-948)</li> <li>Information Disclosure Statement(s) (PTO-1449 or PTO/SB/0 Paper No(s)/Mail Date</li> </ol>		ate Patent Application (PTO-152)				

Application/Control Number: 10/010,237 Page 2

Art Unit: 2822

### **DETAILED ACTION**

1. This action is in response to the request for continued examination filed October 17, 2003.

## Response to Arguments

2. Applicant's arguments with respect to claims 1-17 have been considered but are moot in view of the new ground(s) of rejection.

#### Continued Examination Under 37 CFR 1.114

3. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 10/17/03 has been entered.

# Claim Rejections - 35 USC § 112

4. The following is a quotation of the first paragraph of 35 U.S.C. 112:

The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.

5. Claims 1-17 are rejected under 35 U.S.C. 112, first paragraph, as failing to comply with the written description requirement. The claim(s) contains subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention: a) "a surface area of an uncovered peripheral portion of the top surface of the package substrate is no greater than 21% of a total surface area of the top surface of the package

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Art Unit: 2822

substrate, the uncovered peripheral portion defined as a surface area of the top surface of the package substrate between an outside perimeter of the unitary capacitor and a perimeter of the package substrate" (See Claims 1 and 8). Claims 2-7 and 9-17 depend directly or indirectly from a rejected claim and are, therefore, also rejected under 35 U.S.C. 112, first paragraph for the reasons set above.

## Claim Rejections - 35 USC § 102

6. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 7. Claims 8 and 11 are rejected under 35 U.S.C. 102(b) as being anticipated by Schaper (UK Patent No. 2098001A).

In regards to claim 8, Schaper discloses the following:

- a) a semiconductor die (14) mounted on a top portion of a top surface of a package substrate (For Example: See Figure 1);
- b) a unitary capacitor (20) having an aperture formed therein, and mounted on the top surface of the package substrate surrounding the semiconductor die (For Example: See Figure 1); and
- c) the unitary capacitor is configured such that when the unitary capacitor is disposed on a top surface of a package substrate, a surface area of an uncovered peripheral portion of the top surface of the package substrate is no greater than 21% of a total surface area of the top surface of the package substrate, the uncovered peripheral portion defined as a surface area of the top surface of the package substrate between an outside perimeter of the unitary capacitor and a perimeter of the package substrate (For Example: See Figure 1). Note in Figure 1 that the capacitor covers the entire peripheral portion of the substrate, leaving none of the peripheral portion uncovered. Hence, the uncovered peripheral portion of the top surface of the substrate is not greater than 21% of the total surface area of the top surface.

Art Unit: 2822

In regards to claim 11, Schaper discloses the following:

a) the aperture is rectangular (For Example: See Figure 1).

## Claim Rejections - 35 USC § 103

- 8. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 9. Claims 1, 2, 3, 5 and 7 are rejected under 35 U.S.C. 103(a) as obvious over Schaper (UK Patent No. 2098001A) in view of Applicant's Prior Art Figures.

In regards to claim 1, Schaper discloses the following:

- a) an unitary capacitor (20) having a bottom surface and a top surface, and an aperture is formed in a central portion thereof extending from the top surface to the bottom surface (For Example: See Abstract and Figure 1).
- b) the unitary capacitor is configured such that when the unitary capacitor is disposed on a top surface of a package substrate (16), a surface area of an uncovered peripheral portion of the top surface of the package substrate is no greater than 21% of a total surface area of the top surface of the package substrate, the uncovered peripheral portion defined as a surface area of the top surface of the package substrate between an outside perimeter of the unitary capacitor and a perimeter of the package substrate (For Example: See Figure 1).

In regards to claim 1, Schaper fails to disclose the following:

a) the bottom surface is provided with electrical connections adapted to be connected to a substrate.

However, Applicant's Prior Art discloses a bottom surface that is provided with electrical connections (For Example: See Figure 1). It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Schaper

Art Unit: 2822

to include a bottom surface that is provided with electrical connections as disclosed in Applicant's Prior Art because it aids in connecting the device with the substrate (For Example: See Paragraph 2).

Additionally, since Schaper and Applicant's Prior Art Figures are both from the same field of endeavor, the purpose disclosed by Applicant's Prior Art Figures would have been recognized in the pertinent art of Schaper.

In regards to claim 2, Schaper discloses the following:

a) aperture is rectangular (For Example: See Figure 1).

In regards to claim 3, Schaper discloses the following:

a) a unitary capacitor that comprises a layer of an electrically conductive material and a layer of a dielectric material (For Example: See Page 3 Lines 23-25).

In regards to claim 5, Schaper fails to disclose the following:

a) electrical connections provided on the bottom surface comprise a ball grid array.

However, Applicant's Prior Art discloses a bottom surface that is provided with electrical connections (For Example: See Figure 1). It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Schaper to include a bottom surface that is provided with electrical connections as disclosed in Applicant's Prior Art because it aids in connecting the device with the substrate (For Example: See Paragraph 2).

Additionally, since Schaper and Applicant's Prior Art Figures are both from the same field of endeavor, the purpose disclosed by Applicant's Prior Art Figures would have been recognized in the pertinent art of Schaper.

Art Unit: 2822

In regards to claim 7, Schaper discloses the following:

a) the aperture is configured to fit over a semiconductor die (For Example: See Figure 1).

In regards to claim 7, Schaper discloses the following:

a) electrical connections are configured for connection to a package substrate on which the semiconductor die is mounted.

However, Applicant's Prior Art discloses a bottom surface that is provided with electrical connections (For Example: See Figure 1). It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Schaper to include a bottom surface that is provided with electrical connections as disclosed in Applicant's Prior Art because it aids in connecting the device with the substrate (For Example: See Paragraph 2).

Additionally, since Schaper and Applicant's Prior Art Figures are both from the same field of endeavor, the purpose disclosed by Applicant's Prior Art Figures would have been recognized in the pertinent art of Schaper.

10. Claim 4 is rejected under 35 U.S.C. 103(a) as obvious over Schaper (UK Patent No. 2098001A) in view of Applicant's Prior Art Figures and Barnett et al. (U.S. Publication No. 2002/0011354).

In regards to claim 4, Schaper fails to disclose the following:

a) the housing of the unitary capacitor is made from a plastic material.

However, Barnett et al. ("Barnett") discloses housing made from plastic (For Example: See Paragraph 0010). It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Schaper to include housing

Art Unit: 2822

made from plastic as disclosed in Barnett because it aids in protecting the device from being damaged (For Example: See Figures 4-7).

Additionally, since Schaper and Barnett are both from the same field of endeavor, the purpose disclosed by Barnett would have been recognized in the pertinent art of Schaper.

11. Claim 6 is rejected under 35 U.S.C. 103(a) as obvious over Schaper (UK Patent No. 2098001A) in view of Applicant's Prior Art Figures and Pape (U.S. Patent No. 6,215,171).

In regards to claim 6, Schaper fails to disclose the following:

a) the unitary capacitor capacitive material comprises co-fired ceramic.

However, Pape discloses capacitive material made from co-fired ceramic (For Example: See Column 8 Lines 10-12). It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Schaper to include capacitive material made from co-fired ceramic as disclosed in Pape because it aids in determining the capacitance of capacitors (For Example: See Column 3 Lines 39-47 and Column 4 Lines 10-26 and Column 4 Lines 64-67).

Additionally, since Schaper and Pape are both from the same field of endeavor, the purpose disclosed by Pape would have been recognized in the pertinent art of Schaper.

12. Claims 9 and 17 are rejected under 35 U.S.C. 103(a) as obvious over Schaper (UK Patent No. 2098001A) in view of Komiya et al. (U.S. Publication No. 2002/0011662).

In regards to claim 9, Schaper fails to disclose the following:

a) electronic component mounted on a top surface of the capacitor.

However, Komiya et al. ("Komiya") discloses the use of an electronic component mounted on a top surface of a capacitor (For Example: See Figure 5). It would have been

Art Unit: 2822

obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Schaper to include the use of an electronic component mounted on a top surface of a capacitor as disclosed in Komiya because it aids in reducing the inductance (For Example: See Paragraph 5).

Additionally, since Schaper and Komiya are both from the same field of endeavor, the purpose disclosed by Komiya would have been recognized in the pertinent art of Schaper.

In regards to claim 17, Schaper fails to disclose the following:

a) the capacitor is mounted on the package substrate via a ball grid array.

However, Komiya discloses the use of a ball grid array (For Example: See Figure 1). It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Schaper to include a ball grid array as disclosed in Komiya because it aids in providing low impedance connections (For Example: See Paragraph 24).

Additionally, since Schaper and Komiya are both from the same field of endeavor, the purpose disclosed by Komiya would have been recognized in the pertinent art of Schaper.

13. Claim 10 is rejected under 35 U.S.C. 103(a) as obvious over Schaper (UK Patent No. 2098001A) in view of Tigelaar et al. (U.S. Patent No. 4,827,323).

In regards to claim 10, Schaper fails to disclose the following:

a) a second capacitor mounted on the first capacitor.

However, Tigelaar et al. ("Tigelaar") discloses capacitors stacked on each other (For Example: See Column 1 Lines 31-57). It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Schaper to

Art Unit: 2822

include capacitors stacked on each other as disclosed in Tigelaar because they aid in increasing capacitance (For Example: See Column 1 Lines 31-57).

Additionally, since Schaper and Tigelaar are both from the same field of endeavor, the purpose disclosed by Tigelaar would have been recognized in the pertinent art of Schaper.

14. Claims 12, 13 and 14 are rejected under 35 U.S.C. 103(a) as obvious over Schaper (UK Patent No. 2098001A) in view of Mamodaly et al. (U.S. Patent No. 4,839,712).

In regards to claim 12, Schaper fails to disclose the following:

a) the capacitor comprises a housing.

However, Mamodaly et al. ("Mamodaly") discloses a capacitor that has housing (For Example: See Figure 6). It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Schaper to include a capacitor that has housing as disclosed in Mamodaly because it aids in supplying the bias (For Example: See Abstract).

Additionally, since Schaper and Mamodaly are both from the same field of endeavor, the purpose disclosed by Mamodaly would have been recognized in the pertinent art of Schaper.

In regards to claim 13, Schaper discloses the following:

a) capacitor comprises a capacitive material (For Example: See Page 3 Lines 23-25).

In regards to claim 13, Schaper fails to disclose the following:

a) housing.

However, Mamodaly discloses a capacitor that has housing (For Example: See Figure 6). It would have been obvious to one having ordinary skill in the art at the time the invention was

Art Unit: 2822

made to modify the semiconductor device of Schaper to include a capacitor that has housing as disclosed in Mamodaly because it aids in supplying the bias (For Example: See Abstract).

Additionally, since Schaper and Mamodaly are both from the same field of endeavor, the purpose disclosed by Mamodaly would have been recognized in the pertinent art of Schaper.

In regards to claim 14, Schaper discloses the following:

- a) the capacitive material comprises a layer of an electrically conductive material and a layer of a dielectric material (For Example: See Page 3 Lines 23-25).
- 15. Claim 15 is rejected under 35 U.S.C. 103(a) as obvious over Schaper (UK Patent No. 2098001A) in view of Mamodaly et al. (U.S. Patent No. 4,839,712) and Barnett et al. (U.S. Publication No. 2002/0011354).

In regards to claim 15, Schaper fails to disclose the following:

a) the housing is made from a plastic material.

However, Barnett discloses housing made from plastic (For Example: See Paragraph 0010). It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Schaper to include housing made from plastic as disclosed in Barnett because it aids in protecting the device from being damaged (For Example: See Figures 4-7).

Additionally, since Schaper and Barnett are both from the same field of endeavor, the purpose disclosed by Barnett would have been recognized in the pertinent art of Schaper.

Art Unit: 2822

16. Claim 16 is rejected under 35 U.S.C. 103(a) as obvious over Schaper (UK Patent No. 2098001A) in view of Mamodaly et al. (U.S. Patent No. 4,839,712) and Pape (U.S. Patent No. 6,215,171).

In regards to claim 16, Schaper fails to disclose the following:

a) the housing comprised co-fired ceramic.

However, Barnett discloses housing made from co-fired ceramic (For Example: See Paragraph 0024). It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Schaper to include capacitive and housing material made from co-fired ceramic as disclosed in Barnett because it aids in providing high density and low cost devices (For Example: See Paragraphs 1-3).

Additionally, since Schaper and Barnett are both from the same field of endeavor, the purpose disclosed by Barnett would have been recognized in the pertinent art of Schaper.

b) the capacitive material comprised of co-fired ceramic.

However, Pape discloses capacitive material made from co-fired ceramic (For Example: See Column 8 Lines 10-12). It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Schaper to include capacitive material made from co-fired ceramic as disclosed in Pape because it aids in determining the capacitances of capacitors (For Example: See Column 3 Lines 39-47 and Column 4 Lines 10-26 and Column 4 Lines 64-67).

Additionally, since Schaper and Pape are both from the same field of endeavor, the purpose disclosed by Barnett would have been recognized in the pertinent art of Schaper.

Page 12

Application/Control Number: 10/010,237

Art Unit: 2822

### Conclusion

17. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Monica Lewis whose telephone number is 571-272-1838.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Amir Zarabian can be reached on 571-272-1852. The fax phone number for the organization where this application or proceeding is assigned is 703-308-7722 for regular and after final communications. Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 703-308-0956.

ML March 2, 2004

> Mary Wilczewski Primary Examiner